Applicable standard						
Rating	Operating temperature range		-40 °C to +105°C (Note1)	Storage temperature range	-10 °C to +60°C (Note3)	
	Operating humidity range		20% to 80% (Note2)	Storage humidity range	40% to 70% (Note3)	
	Applicable connector		DF62#-24S-2.2C(**)	Voltage	250V AC/DC	
	UL, C-UL Rating	Voltage	250V AC/DC △2	Current	AWG #22 : 2.5A AWG #24 : 2.0A AWG #26 to 30 : 1.0A	
		Current	2.5A			
		Operating temperature range	-35℃～75℃(Note1)			

Specifications

Item	Test method	Requirements	QT	AT
Construction				
General examination	Visually and by measuring instrument.	According to drawing.	X	X
Marking	Confirmed visually.		X	X
Electric characteristics				
Contact resistance	20mV MAX, 1mA (DC or 1000Hz).	30 mΩ MAX.	X	–
Insulation resistance	500 V DC.	1000 MΩ MIN.	X	–
Voltage proof	650 V AC for 1 min.	No flashover or breakdown.	X	–
Mechanical characteristics				
Mechanical operation	30 times insertion and extraction.	①Contact resistance: 30 mΩ MAX. ②No damage, crack or looseness of parts.	X	–
Vibration	Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.	①No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts.	X	–
Shock	490 m/s^2 duration of pulse 11 ms at 3 times each for 3 both axial directions.	①No electrical discontinuity of 1μs. ②No damage, crack or looseness of parts.	X	–
Environmental characteristics				
Damp heat (Steady state)	Exposed at 40 ± 2℃ , 90 to 95 %, 96 h. (After leaving the room temperature for 1-2h.)	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1000 MΩ MIN. ③No damage, crack or looseness of parts.	X	–
Rapid change of temperature	Temperature -55℃→ +85℃ Time 30min→ 30min Under 5 cycles. (The transferring time of the tank is 2-3 min) (After leaving the room temperature for 1-2h.)	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1000 MΩ MIN. ③No damage, crack or looseness of parts.	X	–
Resistance to Soldering heat	1)Solder bath method Soldered at solder temperature, 260°c for in immersion , duration, 10 s. 2)Manual soldering Soldering iron temperature :300℃, Soldering time :3s. No strength on contact.	No deformation of case of excessive looseness of the terminals.	X	–
Solderability	Soldered at solder temperature, 245°c for in immersion , duration, 5 s.	A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed.	X	–

Remarks
Note 1: Include the temperature rising by current.
Note 2: No condensing.
Note 3: Apply to the condition of long term storage for unused products before mounted on PCB.
After mounted on PCB, operation temperature and humidity range is applied for interim storage during transportation.

	Count	Description of revisions	Designed	Checked	Date
△2	1	DIS-H-00019309	RI.GENDA	SZ.ONO	20231023

Unless otherwise specified, refer to IEC 60512.

Approved	HS.OKAWA	20160902
Checked	TS.FUKUSHIMA	20160902
Designed	TS.MIYAKI	20160902
Drawn	TS.MIYAKI	20160902

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

		Drawing no.	ELC-362875-01-00	
HRS	Specification sheet	Part no.	DF62-24P-2.2DS(01)	
	Hirose electric co., ltd.	Code no.	CL0544-0583-0-01 △2	1/1

FORM HD0011-2-1